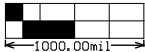
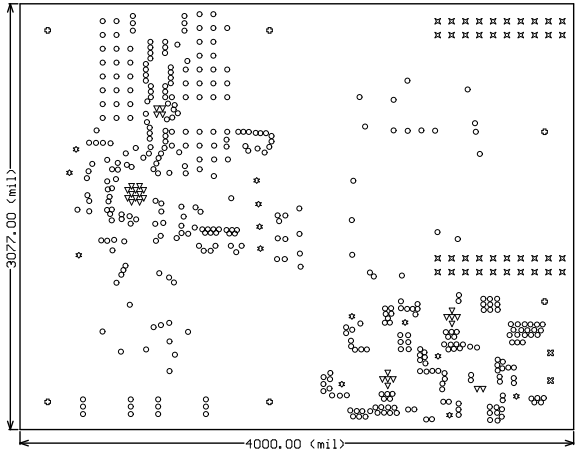


Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	Rogers4003C	9.50mil	4.8	
5	GND	Copper	1.40mil		
6	Dielectric 3	FR-4	35.00mil	4.8	
7	POWER	Copper	1.40mil		
8	Dielectric 2	FR-4	9.50mil	4.8	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

20mils width on top layer should be controlled 50 ohms +/- 5%

Symbol	Hit Count	Tool Size	Plated	Hole Type
▽	28	7.874mil (0.2mm)	PTH	Round
○	420	12mil (0.305mm)	PTH	Round
×	40	40mil (1.016mm)	PTH	Round
※	2	51.181mil (1.3mm)	PTH	Round
☆	13	63mil (1.6mm)	PTH	Round
◇	6	157mil (3.988mm)	NPTH	Round
	509 Total			

Drill Table
FOR 7.874MIL DRILL +0/-7.874MIL
FOR 12MIL DRILL +0/-12MIL
FOR PTH DRILL +/-3MIL
FOR NPTH DRILL +/-2MIL



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00626	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-00626		
PLOT NAME = Drill Drawing For (Bottom Layer)	DATE: 5/6/2016	2:11:09 PM	TEXAS INSTRUMENTS

Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
4000MIL X 3077MIL

Number of Layers: 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 19.69MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
☒ FR-408 ☐ FR4 High Tg ☒ RO4003C

THICKNESS: ☒ 63 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/-

COPPER THICKNESS (FINISHED):
OUTER: ☒ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☐ 2.8MIL (2oz)
INNER SIGNAL: ☒ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☐ N/A

DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER

BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER

SOLDER RESIST COLOR:
☒ GREEN ☐ BLUE ☐ OTHER

SURFACE FINISH: ☒ IMMERSION GOLD (ENG) ☐ ENERPIG
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1
☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER

ADDITIONAL REQUIREMENTS: VIA TENTING: YES ☒ NO ☐
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
MANUFACTURER'S UL: ☐ RAIL ☐ METAL ☒ SILK

Notes Not put solder on UI (LHX2592 IC) footprint if IC is not installed.



PROJECT TITLE: CW RF SIGNAL GENERATOR	LAYOUT BY: Manjunatha T N
DESIGNED FOR: Public Release	ALTIM DESIGNER VERSION: 14.3.14.34663
FILE NAME: TIDA-00626.PcbDoc	SCALE: 0.72
ENGINEER: Skariah, Leni	